CLAIMS

Sub a1

1. ~~A mounted electrophoretic display assembly, comprising:~~
   a flexible substrate;
   an electrical connection formed on said flexible substrate and having first and second contact pads spaced from one another;
   an electrophoretic display element in electrical communication with said first contact pad; and
   a control circuit mounted on said flexible substrate and in electrical communication with said second contact pad.

2. The display assembly of claim 1, wherein said control circuit is connected to said second contact pad with a curable, electrically conductive thermoset.

3. The display assembly of claim 1, wherein said control circuit is connected to said second contact pad with an electrically conductive ink.

4. The display assembly of claim 1, wherein said control circuit is connected to said second contact pad with an electrically conductive paint.

5. The display assembly of claim 1, wherein said control circuit is connected to said second contact pad by being removably mounted in a control circuit carrier that is in electrical communication with said second contact pad.

6. The display assembly of claim 1 wherein said control circuit comprises an electrophoretic display driver chip.

7. A method of manufacturing an electrophoretic display assembly, comprising the steps of:
   providing a ~~flexible substrate;~~

forming upon said substrate an electrical connection having a first contact pad and a second contact pad spaced from one another;

mounting upon said substrate a control circuit in electrical communication with said second contact pad; and

providing an electrophoretic display element in electrical communication with said first contact pad.

8. The method of claim 7, wherein the step of forming upon said substrate an electrical connection comprises a printing process.

9. The method of claim 7, wherein the step of providing an electrophoretic display element comprises a printing process.

10. A method of manufacturing an electrophoretic display assembly, comprising the steps of:

providing a first flexible substrate;

forming upon said first flexible substrate an electrical connection having a first contact pad and a second contact pad separated from each other;

mounting on said first flexible substrate a control circuit in electrical communication with said second contact pad;

providing a second flexible substrate;

disposing upon said second flexible substrate an electrophoretic display element; and

disposing said first flexible substrate adjacent said second flexible substrate so that said first contact pad addresses said electrophoretic display element.

11. The method of claim 10, wherein the step of disposing upon said second flexible substrate an electrophoretic display element comprises a printing process.

12. The method of claim 10, wherein the step of disposing said first flexible substrate adjacent said second flexible substrate further comprises a laminating process.